KAMAYA OHM

Spec. No.: RLP-K-HTS-0001 /12

Date: 2022. 12. 31

Data sheet

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

Style: RLP16,20,32,63, MLP20,63

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature: $+5^{\circ}\text{C} \sim +35^{\circ}\text{C}$ Relative humidity: $25\% \sim 75\%$

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

No: RLP-K-HTS-0001 /12

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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1. Scope

1.1 This data sheet covers the detail requirements for metal-plate chip resistor; low ohm, style of RLP16, 20, 32, 63, MLP20, 63.

1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014

2. Classification

Type designation shall be the following form.

(Example)

RLP	63	K	R010	F	TE
1	2	3	4	5	6
Sty	/le				

1 Metal - plate chip resistor; low ohm

2 Size

RLP16	1608 size, 0.33W
RLP20	2012 size, 0.5W
RLP32	3216 size, 1W
RLP63	6332 size, 1W
MLP20	2012 size, 1W
MLP63	6332 size, 2W

3 Temperature coefficient of resistance

N	±70×10 ⁻⁶ / °C
K	±100×10 ⁻⁶ / °C
(Doob)	±150×10 ⁻⁶ / °C
-(Dash)	±250×10 ⁻⁶ / °C

4 Rated resistance

1L50	1.5mΩ
R002	2mΩ

5 Tolerance on rated resistance

F	±1%
J	±5%

6 Packaging form

TP	Paper taping
TE	Embossed taping

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3. Rating

3.1 The ratings shall be in accordance with Table-1.

3.1.1 RLP series

Table-1(1)

	Dated discipation		Temperature		Rated resistance	Tolerance on rated									
Style	Rated dissipation (W)	Rated current (A)	resistance	(10 ⁻⁶ /°C)	$(m\Omega)$	resistance									
		0.4	K	100											
DI DAO		8.1	N	±70	- 5										
RLP16	16 0.33	P16 0.33		K	100										
		5.7	N	±70	10										
			K	100											
		15.8	N	±70	2										
			K	100											
		11.1	N	±70	4										
			K	100											
		10.0	N	±70	5										
			K												
RLP20	0.5	9.1		100	6										
			N	±70											
		7.9	K	100	8										
			N	±70	Ů										
		7.4	K	100	9										
		7.1	N	±70	•										
		7.0	K	100	10										
		7.0	N	±70	10										
		31.6	-(Standard)	±150	1										
		01.0	K	±100	'										
			22.3	K	±100	2									
		22.3	N	±70] 2										
			18.2	K	±100	2									
	10.2	N	±70	3	F(±1%)										
			15.8	K	±100	- 4	J(±5%)								
							15.6	N	±70	4					
												14.1	K	±100	-
		14.1	N	±70	5										
			40.0	K	±100	0									
				12.9	N	±70	- 6								
													44.0	K	±100
		11.9	N	±70	7										
DI Doo		44.4	K	±100	0										
RLP32	1.0	11.1	N	±70	- 8										
		40.5	K	±100	_										
	10.5	N	±70	9											
			K	±100	46										
	10	N	±70	10											
		K	±100	44											
	9.5	N	±70	11											
	_	K	±100												
		9.1	N	±70	12										
	_	K	±100												
	8.7	N	±70	13											
		K	±100												
		8.4	N	±70	14										
			K	±100											
		8.1	N N		15										
				IN	±70										

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Table-1(2)

Style	Rated dissipation (W)	Rated current (A)	Temperature resistance	coefficient of	Rated resistance (mΩ)	Tolerance on rated resistance
			-(Standard)	±150	,	
	2.0	44.7	K	±100	1	
			N	±70		
		22.3	K	±100	2	
		22.3	N	±70	2	
		18.2	K	±100	3	
		10.2	N	±70	3	
		15.8	K	±100	4	
		10.0	N	±70	7	
		14.1	K	±100	5	F(±1%) J(±5%)
			N	±70	J	
		12.9	K	±100	6	
RLP63			N	±70		
	10	1.0 11.9	K	±100	7	
	1.0		N	±70	,	
		11.1	K	±100	8	
			N	±70		
		10.5	K	±100	9	
		10.0	N	±70		
		9.1	K	±100	10	
			N	±70	10	
			K	±100	12	
		• • • • • • • • • • • • • • • • • • • •	N	±70		
		8.1	K	±100	15	
		5.1	N	±70		

3.1.2 MLP series

Table-1(3)

			iabie-i(J)			
Style	Rated dissipation	Rated current	Temperature coefficient of		Rated resistance	Tolerance on rated	
Otyle	(W)	(A)	resistance	(10 ⁻⁶ / °C)	$(m\Omega)$	resistance	
MLP20	1.0	10	K	100	10		
IVILI 20	1.0	10	N	±70	10		
		31.6	K	100	2		
		31.0	N	±70	2		
		25.8	K	100	3		
		23.0	N	±70	S		
	MLP63 2.0	00.0	K	100	4		
		2	22.3	N	±70	4	
		20	K	100	5		
			20	N	±70	3	F(±1%) J(±5%)
MI P63			18.2	K	100	6	
IVILI 00			10.2	N	±70		
		16.9	K	100	7		
		10.9	N	±70			
		45.0	K	100	8		
	15.8	N	±70	0			
		14.9	K	100	9		
		14.9	N	±70	3		
		14.1	K	100	10		
		14.1	N	±70			

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Style	Insulation voltage (V)	Category temperature range (°C)
RLP10		
RLP16		
RLP20		
RLP32	100	<i>–</i> 55∼+155
RLP63		
MLP20		
MLP63		

3.2 Climatic category

55/155/56 Lower category temperature –55 °C

Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long–term tests $\pm 5\%$ -for short–term tests $\pm 1\%$

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

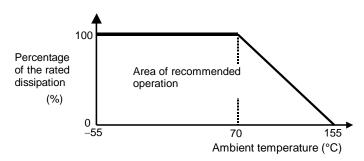


Figure-1 Derating curve

3.5 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (
$$\Omega$$
)

3.6 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

I: Rated current (A)
$$I = \sqrt{P / R}$$
P: Rated dissipation (W)
R: Rated resistance (Ω)

The rated current shall be corresponding to rated voltage.

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4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RLP16, 20, 32, MLP20
TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RLP63, MLP63

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

5.1.1 RLP series

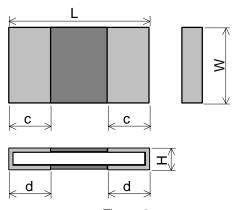


Figure-2 Table-3(

-3(1)	Unit: mm

Style	Rated resistance (m Ω)	L	W	Н	С	d
RLP16	5	1.6±0.1	0.8±0.1	0.35±0.10	0.2±0.1	0.6±0.1
KLP10	10	1.0±0.1	0.0±0.1	0.3±0.1	0.2±0.1	0.3±0.1
	2			0.22±0.10	0.35±0.10	0.55±0.20
	4			0.35±0.10	0.35±0.10	0.75±0.20
	5			0.35±0.10	0.35±0.10	0.6±0.2
RLP20	6	2.0±0.15	1.25±0.15	0.35±0.10	0.35±0.10	0.47±0.20
	8			0.22±0.10	0.35±0.10	0.6±0.2
	9			0.22±0.10	0.35±0.10	0.52±0.20
	10			0.22±0.10	0.35±0.10	0.47±0.20
	1			0.32±0.15	1.1±0.25	1.1±0.25
	2			0.32±0.15	0.5±0.25	0.5±0.25
	3			0.35±0.10	0.7±0.25	1.3±0.25
	4			0.35±0.10	1.1±0.25	1.1±0.25
	5			0.35±0.10	1.0±0.25	1.0±0.25
	6			0.35±0.10	0.85±0.25	0.85±0.25
	7			0.35±0.10	0.7±0.25	0.7±0.25
RLP32	8	3.2±0.15	1.6±0.15	0.35±0.10	0.6±0.25	0.6±0.25
112.02	9	0.220.10	11020110	0.3±0.1	0.75±0.25	0.75±0.25
	10			0.28±0.10	0.5±0.25	0.5±0.25
	11			0.28±0.10	0.5±0.25	0.5±0.25
	12			0.22±0.10	0.65±0.25	0.65±0.25
	13			0.22±0.10	0.65±0.25	0.65±0.25
	14			0.22±0.10	0.55±0.25	0.55±0.25
	15			0.22±0.10	0.5±0.25	0.5±0.25

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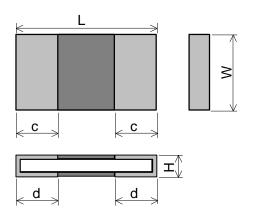


	Table-3(2)							
Style	Rated resistance (m Ω)	L	W	Н	С	d		
	1		3.2±0.25	0.38±0.15	2.2±0.25	2.2±0.25		
	2			0.38±0.15	1.1±0.25	1.1±0.25		
	3			0.45±0.15	2.2±0.25	2.2±0.25		
	4			0.35±0.15	2.2±0.25	2.2±0.25		
	5			0.34±0.15	1.95±0.25	1.95±0.25		
RLP63	6	6.3±0.25		0.34±0.15	1.75±0.25	1.75±0.25		
KLF03	7	0.3±0.23	3.1±0.25	0.35±0.15	1.4±0.25	1.4±0.25		
	8			0.35±0.15	1.1±0.25	1.1±0.25		
	9			0.35±0.15	0.8±0.25	0.8±0.25		
	10			0.23±0.15	1.75±0.25	1.75±0.25		
	12			0.23±0.15	1.4±0.25	1.4±0.25		
	15			0.23±0.15	0.95±0.25	0.95±0.25		

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5.1.2 MLP series

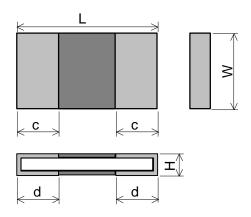


Table-3(3)

Unit: mm

Style	Rated resistance (m Ω)	L	Ŵ	Н	С	d
MLP20	10	2.0±0.15	1.25±0.15	0.22±0.10	0.33±0.15	0.47±0.20
	2			0.58±0.15	2.2±0.25	2.2±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
	4			0.34±0.15	2.2±0.25	2.2±0.25
	5			0.51±0.15	1.1±0.25	1.1±0.25
MLP63	6	6.3±0.25	3.1±0.25	0.5±0.15	1.1±0.25	1.1±0.25
	7			0.5±0.15	0.6±0.25	0.6±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10			0.35±0.15	0.5±0.25	0.5±0.25

5.2 Net weight (Reference)

	,	
Style	Rated resistance (m Ω)	Net weight (mg)
RLP16	5,10	2
RLP20	2, 4 to 6 , 8 to 10	3
RLP32	1 to 3	12
NLF32	4 to 15	11
RLP63	1,2	47
KLP03	3 to 10,12 15	43
MLP20	10	3
MLP63	2 to 10	60

6. Marking

The Rated resistance of RLP16 should not be marked standard.

6.1 RLP63, MLP63

The rated resistance shall be marked in 4 characters consisting of 3 figures and a letter and marked on over coat side.

(Example) "R010" \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]

"1L50" \rightarrow 0.0015 [Ω] \rightarrow 1.5 [m Ω]

6.2 RLP20, 32, MLP20

The rated resistance shall be marked in combination of two figures and underlines and marked on over coat side.

(Example) " $\underline{05}$ " \rightarrow 0.005 [Ω] \rightarrow 5 [m Ω]

" $\underline{10}$ " \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]

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7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items		IADIE-4	` '		Performance requirements	
			Condition of test (JIS C 52	01–1)		
1	Visual examination	Sub-clause				As in 4.4.1	
		Checked b	y visual examina	ition.			The marking shall be legible, as
	6.		1.10				checked by visual examination.
2	Dimension	Sub-clause	e 4.4.2				As specified in Table-3 of this
	Decistores	Danistanas	والمواو وباوري				specification.
	Resistance		value shall be			ounting	As in 4.5.2 The resistance value shall
		li le substia	te of the following	y corialic	JI I.		The resistance value shall correspond with the rated
		0	b	ont			resistance taking into account the
		Current terminal	term				specified tolerance.
				$ _{-}$:Copper	clad	specified tolerarioe.
		Vo	oltage terminal		:Solder	resist	
					Unit	t:mm	
		Style	Resistance	0	b	_	
		Style	value(m Ω)	а	D	С	
		RLP16	5	0.6	8.0	0.9	
		INLETIO	10,	1.0	0.6	0.9	
		RLP20	2	0.5	1.1	1.36	
		INLI 20	4 to 6, 8 to 10	8.0	0.95	1.50	
			1	1.0	1.45		
			2	2.1	0.9		
		RLP32	3	8.0	1.55	1.7	
			4	1.0	1.45		
			5 and 6	1.4	1.25		
			7 to 15	2.1	0.9		
			1	1.5	3.0	4.0	
		51.500	2	4.0	1.8		
		KLP63				3.5	
			_				
		MIDOO				1.00	
		IVILPZU				1.30	
						3.5	
		Thickness					
				aratus co	orresnon	dina to	
				J. 7 J. 11	. 525 101		
		Thickness 4-Terminal Measurem Note: The DC Low-c	RLP63 3,4 1.8 2.9 5 2.4 2.6 6 to 10,12,15 4.0 1.8 MLP20 10 0.8 0.95 1.36				

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Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
3	Voltage proof	Sub-clause 4.7	No breakdown or flash over
		Method: 4.6.1.4(See Figure-5)	
		Test voltage: Alternating voltage with a peak value	
		of 1.42 times the insulation voltage.	
		Duration: 60 s±5 s	
		Insulation resistance	R≥1 GΩ
		Test voltage: Insulation voltage	_
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
-		Without aging	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2 s.	coating.
		Bath temperature: 235 °C±5 °C	- oodan igi
		Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
3	IVIOUITIIIII	Substrate material: Epoxide woven glass	
	Overload	Test substrate: RLP16: Figure–3–1	
	(in the mounted state)	RLP20, MLP20 Figure–3–2	
	(in the mounted state)	RLP32 Figure–3–3	
		RLP63, MLP63 Figure-3-4	
		Sub-clause 4.13	
		The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s	No visible demage
		Visual examination	No visible damage
	Solvent resistance of the	Resistance	$\Delta R \le \pm 1\%$
		Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure 4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3mm(RLP16, 20, 32, MLP20)	
		1 mm(RLP63, MLP63)	
		Resistance	ΔR ≤ ±1%
	Final measurements	Sub-clause 4.33.6	
		Visual examination	No visible damage
		viodai ondifiliation	J -

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Table-4(3)

	1able-4(3)								
No	Test items Cor		ns	Condition of test (JIS C 5201–1)	Performance requirements				
7	Resistance heat	to	soldering	Sub-clause 4.18 (JEITA RC-2144 2.3.2) Substrate material: Epoxide woven glass Test substrate: Figure-3-1 T1:Pre-heat minimum temp.:150±5 °C T2:Pre-heat maximum temp.:180±5 °C T3:Soldering temp.:220 °C T4:Peak temp.:260 °C t1:Pre-heat duration:120±5 s t2:Soldering duration:60 to 90 s t3:Peak duration(T4-5°C):20 to 40 s Pre-reflow soldering: 1 time (Initial measurements) Reflow soldering: 3 times T4 T3 T2 T1	1 enormance requirements				
	Component resistance		solvent	Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 2 Recovery: 48 h Visual examination Resistance	No visible damage $ \Delta R \leq \pm 1\% $ No visible damage $ \Delta R \leq \pm 1\% $				
8	Mounting Adhesion			Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3–1 Sub-clause 4.32 Force: 5 N					
	Rapid chang	e ter	nperature	Duration: 10 s±1 s Visual examination Sub–clause 4.19 Lower category temperature:–55 °C Upper category temperature:+155 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination Resistance	No visible damage $\label{eq:local_problem} \begin{tabular}{ll} No visible damage \\ $\Delta R \le \pm 1\% \end{tabular}$				

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Table-4(4)

	<u> </u>	1abic 4(4)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	-Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature −55 °C	
		Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4.23.7	
		The applied current shall be the rated current.	
		Duration: 1 min.	No visible damage
		Visual examination	$\Delta R \le \pm 5\%$
		Resistance	AIX = 10 /0
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: RLP16: Figure–3–1	
		RLP20, MLP20 Figure-3-2	
		RLP32 Figure–3–3	
	F 1 170.00	RLP63, MLP63 Figure-3-4	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h on	
		and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	No visible damage
		Visual examination	$\Delta R \le \pm 5\%$
		Resistance	∆IX ≥ ±J /0
11	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Madaga at a st	Test substrate: Figure–3–1	
	Variation of resistance with	Sub-clause 4.8	As in Table–1
	temperature	+20 °C / +155 °C	

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Table-4(5)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1	
Damp heat, steady state		Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination Resistance	No visible damage Legible marking ΔR ≤ ±5%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table-4
	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1	
	Endurance at upper category temperature	Sub-clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h:	No visible damage
		Visual examination Resistance	$\Delta R \le \pm 5\%$

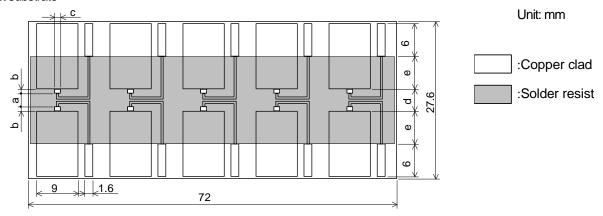
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METAL-PLATE CHIP RESISTOR; LOW OHM RLP10, 16, 20, 32, 63, MLP20, 63

8. Test substrate



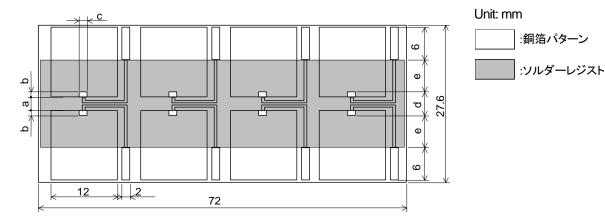
Style	Rated resistance (m Ω)	а	b	С	d	е	
RLP16	5	0.6	0.9	0.0	2.2	6.2	
KLF10	10	1.0	0.6	c d 0.9 2.2 1.36 2.7 1.7 3.9 3.5 7.6 1.36 2.7 3.5 7.6	2.2	0.2	
DI DOO	2	0.5	1.1	1.26	2.7	E OE	
RLP20	4 to 6, 8 to 10	8.0	0.95	1.30	2.1	5.95	
	1	1.0	1.45				
	2	2.1	0.9				
DI DOO	3	0.8	1.55	47	2.0	E 25	
RLP32	4	1.0	1.45	1.7	3.9	5.35	
	5 and 6	1.4	1.25				
	7 to 15	2.1	0.9				
	1	1.5	3.05				
	2	4.0	1.8				
RLP63	3, 4	1.8	2.9	3.5	7.6	3.5	
	5	2.4	2.6				
	6 to 10,12,15	4.0	1.8				
MLP20	10	0.8	0.95	1.36	2.7	5.95	
MI DCO	2 to 4	1.8	2.9	2.5	7.0	2.5	
MLP63	5 to 10	4.0	1.8	3.5	7.6	3.5	

Figure-3-1 RLP, MLP TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm Title: METAL-PLATE CHIP RESISTOR; LOW OHM RLP10, 16, 20, 32, 63, MLP20, 63

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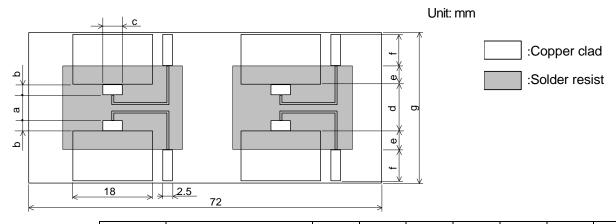


Style	Rated resistance (m Ω)	а	b	С	d	е
RLP20	2	0.5	1.1			
KLP20	4 to 6, 8 to 10	to 6, 8 to 10 0.8 0.95 1.3		1.36	1.36 2.7	
MLP20	10	0.8	0.95			

Figure-3-2 RLP20, MLP20 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



Style	Rated resistance (m Ω)	а	b	С	d	е	f	g
	1	1.0	1.45				11.68	39
	2	2.1	0.9	4.7	3.9		6.0	27.6
DI DOO	3	0.8	1.55			5.35	6.0	21.0
RLP32	4	1.0	1.45	1.7		5.55	11.68	39
	5 and 6	1.4	1.25				6.0	27.6
	7 to 15	2.1	0.9				6.0	27.6

Figure-3-3 RLP32, MLP32 TEST SUBSTRATE

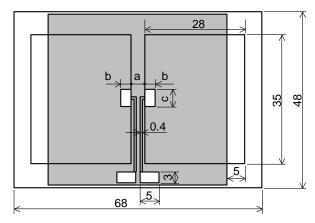
Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

No: RLP-K-HTS-0001

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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Unit: mm				
:Copper clad				
:Solder resist				
Style	Rated resistance $(m\Omega)$	а	b	С
	1	2.0	3.0	4.0
	2	4.0	1.8	
RLP63	3, 4	1.8	2.9	3.5
	5	2.4	2.6	
	6 to 10,12,15	4.0	1.8	
MLP63	2 to 4	1.8	2.9	3.5
	5 to 10	4.0	1.8	

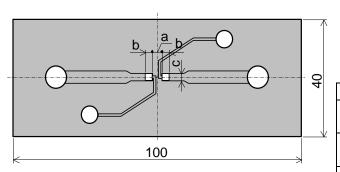
Figure-3-4 RLP63, MLP63 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

Remark: In the case of connection by connector, the connecting terminals are gold plated.

However, the plating is not necessary when the connection is made by soldering.

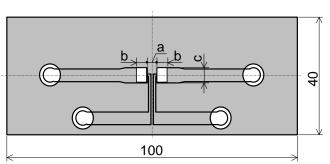


Unit: mm
:Copper clad
:Solder resist

Style	Rated resistance (m Ω)	а	b	С
RLP16	5	0.6	0.9	0.9
KLP 10	10	1.0	0.6	0.9
RLP20	2,3	0.5	1.1	1.36
KLP20	4 to 6, 8 to 10	8.0	0.95	1.30
	1	1.0	1.45	
	4 to 6, 8 to 10 0.8 1 1.0 2 2.1 3 0.8	0.9		
DI Daa	3	0.8	1.55	1.7
RLP32	4	1.0	1.45	
	5 and 6	1.4	1.25	
	7 to 15	2.1	0.9	
MLP20	10	0.8	0.95	1.36

RLP, MLP BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

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Unit: mm		
	:Copper clad	
	:Solder resist	

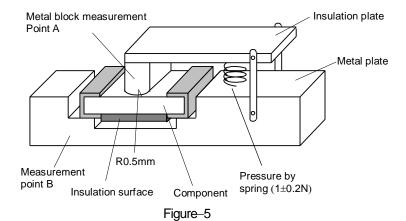
Style	Rated resistance (m Ω)	а	b	С
	1	1.5	3.05	4.0
	2	4.0	1.8	
RLP63	3, 4	1.8	2.9	2.5
	5	2.4	2.6	3.5
	6 to 10,12,15	4.0	1.8	
MLP63	2 to 4	1.8	2.9	2.5
IVILP03	5 to 10	4.0	1.8	3.5

RLP 63, MLP63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Figure-4

Remark. Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

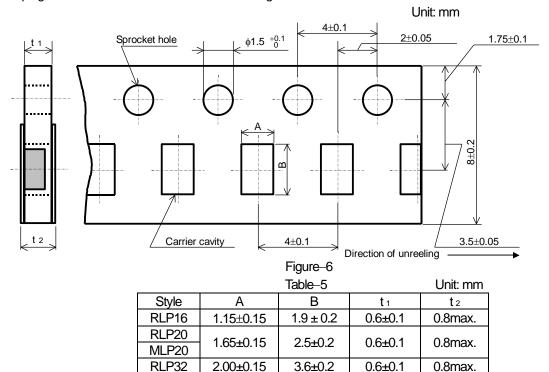


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9. Taping

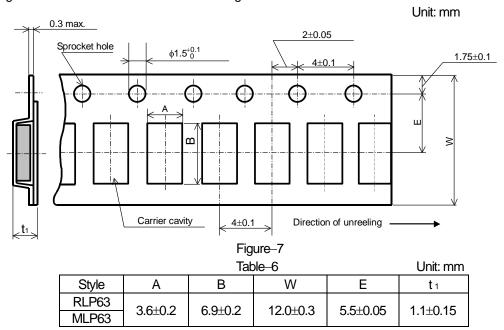
- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.



9.2.2 Embossed taping (12mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-7 and Table-6.



RLP10, 16, 20, 32, 63, MLP20, 63 Page: 18/19

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RLP16, 20, 32, MLP20: Figure–8, RLP63, MLP63: Figure–9.
- 6). When the tape is bent with the minimum radius for (RLP16, 20, 32, MLP20: 25mm, RLP63, MLP63: 30mm) the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

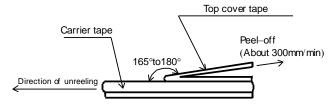


Figure-8

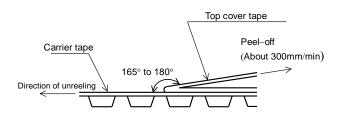


Figure-9

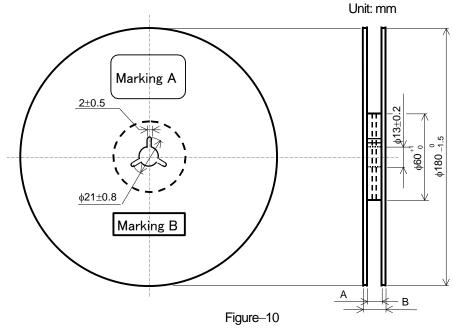
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Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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9.3 Reel dimension

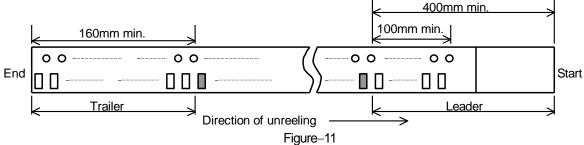
Reel dimensions shall be in accordance with the following Figure–10 and Table–7. Plastic reel (Based on EIAJ ET–7200C)



	900		
	Table-7		Unit: mm
Style	Α	В	Note
RLP16, 20, 32, MLP20	_P20 9 +1.0	11.4±1.0	Injection molding
NLF 10, 20, 32, WLF 20		Vacuum forming	
RLP63, MLP63	13 +1.0	17±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

9.4 Leader and trailer tape.



10. Marking on package

The label of a minimum package shall be legibly marked with follows.

10.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Lot number (3) Quantity (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)

单击下面可查看定价,库存,交付和生命周期等信息

>>Kamaya(釜屋电机)